

Electronic Patent Application Fee Transmittal

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| Application Number: | 10569942 |
| Filing Date: | 28-Feb-2006 |
| Title of Invention: | METHOD FOR MANUFACTURING BONDED WAFER |
| First Named Inventor/Applicant Name: | Akihiko Endo |
| Filer: | Arnold Turk/Sean Shoolbraid |
| Attorney Docket Number: | P29123 |

Filed as Large Entity

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| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
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| Basic Filing: | | | | |
| Pages: | | | | |
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| Miscellaneous-Filing: | | | | |
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| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
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